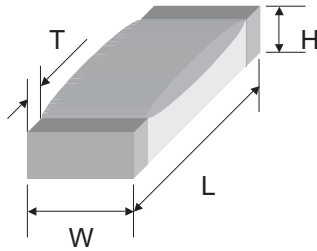


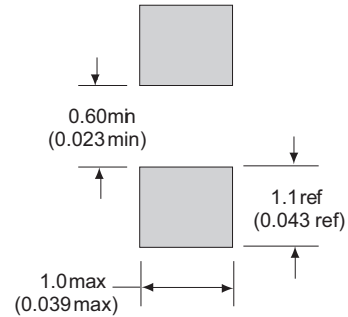
Dimensions - mm (in)



EIA Size	L	W	H	T
0603ESDA	1.60±0.15 (0.063±0.006)	0.80±0.10 (0.031±0.004)	0.60±0.10 (0.024±0.004)	0.31±0.21 (0.012±0.008)

Recommended Pad Layout - in (mm)

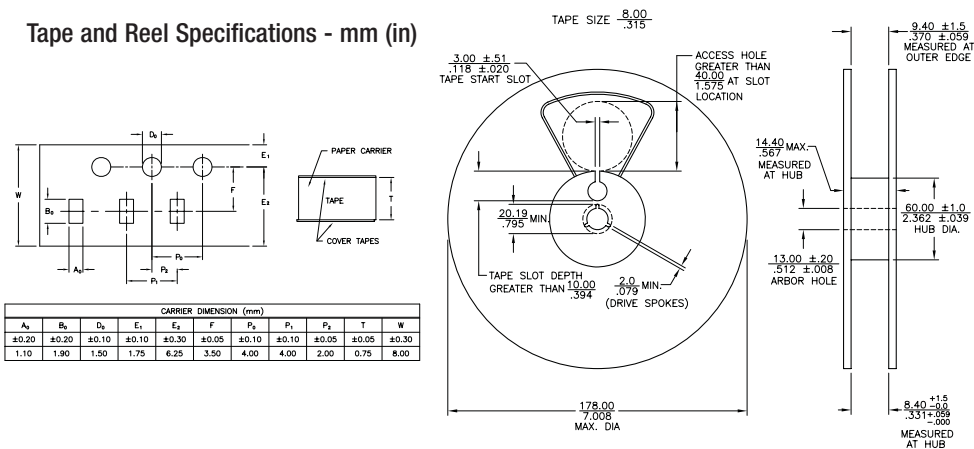
(per IPC-SM-782)



Packaging

- 5000 pieces in paper tape on 7 inch diameter (178mm) reel per EIA Standard 481.

Tape and Reel Specifications - mm (in)



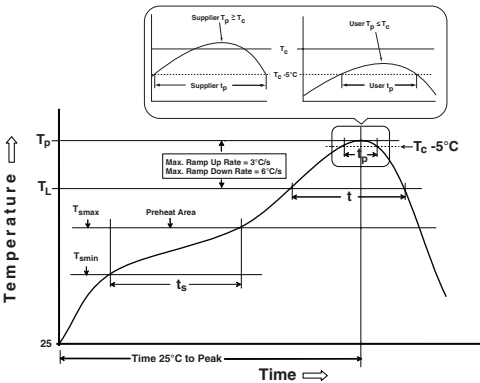
Environmental Specifications:

- Coating bond strength: ASTM D3359-83, Method A, Section 6.
Note: the device coating is not scored.
- Chemical resistance: ASTM D-543, 4 hrs @ 40°C, 3 solutions (H₂O, detergent solution, defluxer).
- Humidity(steady state): MIL-STD-883, method 1004.7, 85% RH, 85°C, 240 hrs.
- Thermal shock: MIL-STD-202F, method 107G, -65°C to 125°C, 30 min, 5 cycles.
- Vibration: MIL-STD-202F,method 201A,(10 to 55 to 10Hz, 1 minute cycle, 2 hrs. each in X-Y-Z axis).
- Solder leach resistance and terminal adhesion per EIA-567.
- Solderability per MIL-STD-202, Method 208 (95% coverage).
- Full load voltage: 14.4Vdc, 1000hrs., 25°C.
- Operating temperature characteristics: Electrical testing at +105°C and -55°C.

Soldering Recommendations

- Compatible with lead and lead-free solder reflow processes
- Peak temperatures and durations:
 - IR Reflow = 260°C max for 30 sec. max. Capable of 3X reflow.
 - Wave Solder = 260°C max. for 10 sec. max.
 - Hand Soldering = 350°C max. for 5 sec. max.

Recommended IR Reflow Profile



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat & Soak		
Temperature min (T _{ssmin})	100°C	150°C
Temperature max (T _{ssmax})	150°C	200°C
Time (T _{ssmin} to T _{ssmax}) (t _s)	60-120 seconds	60-120 seconds
Average ramp-up rate (T _{ssmax} to T _p)	3°C/second max.	3°C/second max.
Liquidous temperature (T _l)	183°C	217°C
Time at liquidous (t _l)	60-150 seconds	60-150 seconds
Peak package body temperature (T _p)*	See classification temp in Table 4.1	See classification temp in Table 4.2
Time (t _p)** within 5°C of the specified classification temperature (T _p)	20** seconds	30** seconds
Average ramp-down rate (T _p to T _{ssmax})	6°C/second max.	6°C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.
** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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Publication No. 4419 BU-SB12433
May 2017



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